

MPPC (S13360 for DUNE)

Nov. 11, 2019

SPECIFICATION SHEET

Structure

Type No. Parameters	S13360 -6050HS-LRQ (S13360-9932)	S13360 -6050HS-HRQ (S13360-9933)	S13360 -6075HS-LRQ (S13360-9934)	S13360 -6075HS-HRQ (S13360-9935)	Unit
Effective photosensitive area	6.0 x 6.0			mm²	
Pixel pitch	50		75		μ m
Number of pixel	14,331		6,364		-
Window	Silicone resin			-	
Window refractive index	1.57			-	
Package	Surface mount type			-	

■ Absolute Maximum Ratings

Parameters	Symbol	Value	Unit
Operating temperature *1	Topr	-196 to +60 (TBD)	°C
Storage temperature *1	Topr	-196 to +80 (TBD)	°C
Maximum temperature cycle (below -40°C to room temperature) *2	-	10 times (TBD)	-
Soldering conditions *3	Tsol	Peak temperature 240 °C x 3 times	-

^{*1:} No condensation

^{*3:} Moisture sensitivity Level: 5A (Defined by IPC/JEDEC J-STD-020E)

■ Electrical and optical characteristics (Typ. T = 25 deg C, Vr = Vop unless otherwise noted)				noted)		
Type No. Parameters	Symbol	S13360 -6050HS-LRQ (S13360-9932)	S13360 -6050HS-HRQ (S13360-9933)	S13360 -6075HS-LRQ (S13360-9934)	S13360 -6075HS-HRQ (S13360-9935)	Unit
Spectral response range	λ	280 to 900		nm		
Peak sensitivity wavelength	λр	450			nm	
Photon detection efficiency at λp *4	-	40 50		%		
Breakdown voltage	Vbr	53 +/- 5		V		
Recommended operating voltage *5	Vop	Vbr + 3.0			V	
Dark count rate	DCR	2.0 (MAX:6.0)		Mcps		
Terminal capacitance at Vop	Ct	1280		pF		
Gain	М	1.7 x 10 ⁶ 4.0 x 10 ⁶		₹ 10 ⁶	-	
Temperature coefficient of reverse voltage	ΔTVop	54		mV/°C		
quenching resistor around room temperature	Rq	280	500 (TBD)	280	500 (TBD)	kΩ
Temperature coefficient of quenching resistor	ΔTRq	Low	High	Low	High	Ω/°C

^{*4 :} Photon detection efficiency does not include crosstalk and after pulse.

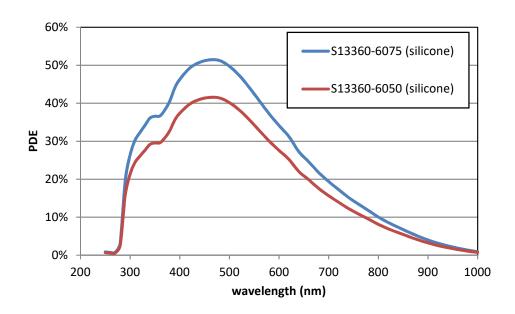
^{*2:} Please avoid rapid temperature change.

^{*5 :} Refer to the data attached for each products.



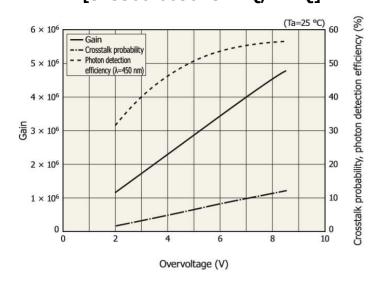
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■ Photon detection efficiency v.s. Wavelength (Vr = Vop = Vbr + 3.0V, measurement example)

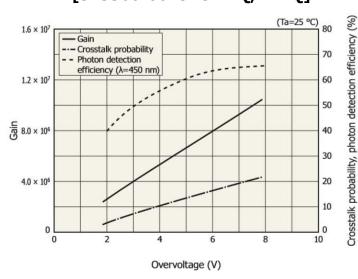


■ Overvoltage specifications of gain, crosstalk probability, photon detection efficiency (Vr = Vop = Vbr + 3.0V, typical example)

[S13360-6050HS-LRQ, -HRQ]



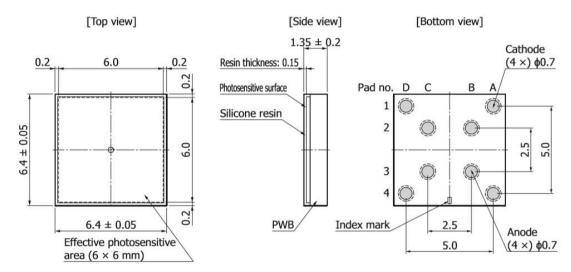
[S13360-6075HS-LRQ, -HRQ]





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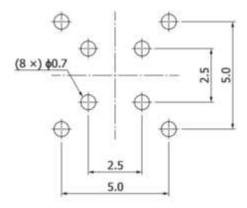
■ Dimensional outline (unit: mm)



Tolerance unless otherwise noted: ±0.1

Pad no.	Connection	
A1, A4, D1, D4	Cathode common	
B2, B3, C2, C3	Anode common	

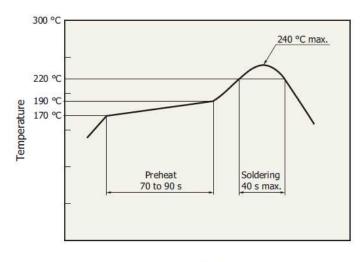
■ Recommended land pattern (unit: mm)





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■ Temperature profile measurement example using our experimental hot-air reflow oven



Time

- This surface mount type package product supports lead-free soldering. After unpacking, store it in an
 environment at a temperature of 25°C or less and a humidity of 60% or less, and perform soldering
 within 24 hours.
- The effect that the product is subject to during reflow soldering varies depending on the circuit board and reflow furnace that are used. Before actual reflow soldering, check for any problems by testing out the reflow soldering methods in advance.
- When three or more months have passed or if the packing bag has not been stored in an environment described above, perform baking in a clean dryer for duration of 24 hours at 125°C.